Tin Whisker Growth Exp.

1,Sample(by package) :SMA 10 Pcs

2. ,Plating thickness : 5um

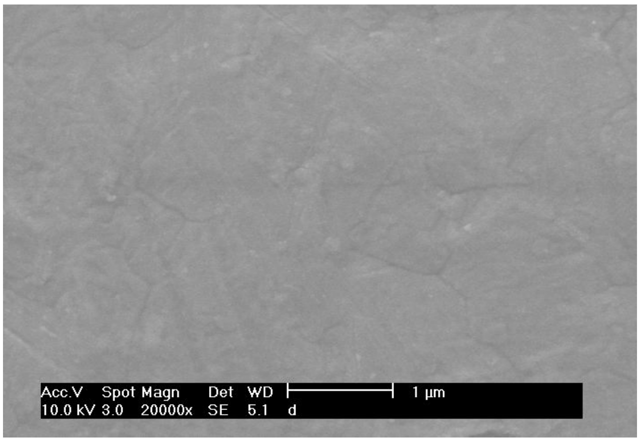
3. Post baking after plating: 150 ℃ for 5 min.

4,Environment condition(Humidity): 85℃,85%RH

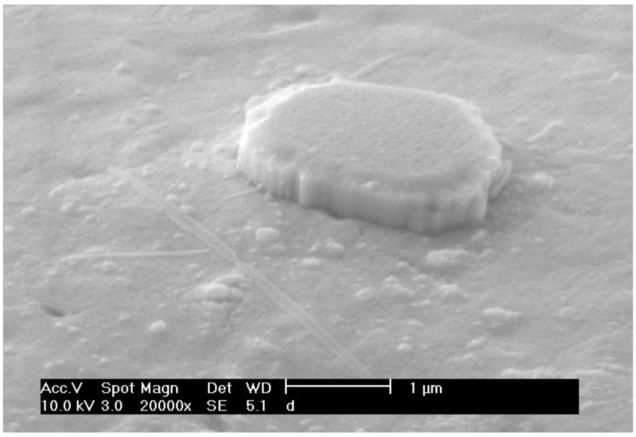
5,Microscope:

PREPARED	DATE	APPROVED	DATE
Xujian	Oct 20,2020	Robert	Oct 20,2020

4-1 After 500Hrs then observed the devices under 20000X microscope



4-2 After 1000Hrs then observed the devices under 20000X microscope



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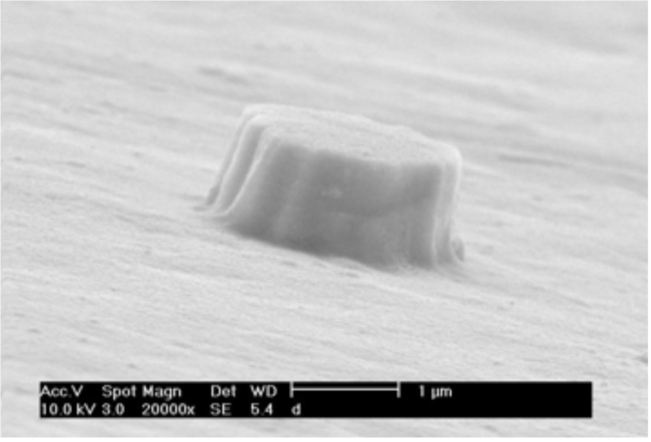
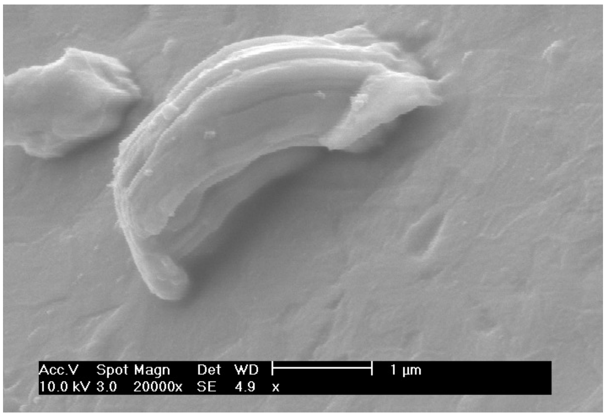
4-3 After 2000Hrs then observed the devices under 20000X microscope



4-4 After 3000Hrs then observed the devices under 20000X microscope



5.Conclusion:

After Humidity condition **85℃,85%RH for 3000 Hrs,** the samples was Observed under 20000X microscope and we found the tin whisker growth up to 4-5um maximum. And, the total numbers of whisker less than 2 pcs in 1 mmx 1mm area.

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